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# **2-Kb and 4-Kb I<sup>2</sup>C Serial EEPROM with Partial Array Write Protection**

#### Description

The CAT24C03/05 is a 2–Kb/4–Kb CMOS Serial EEPROM device organized internally as 16/32 pages of 16 bytes each, for a total of 256x8/512x8 bits. These devices support both Standard (100 kHz) as well as Fast (400 kHz) I<sup>2</sup>C protocol.

Data is written by providing a starting address, then loading 1 to 16 contiguous bytes into a Page Write Buffer, and then writing all data to non-volatile memory in one internal write cycle. Data is read by providing a starting address and then shifting out data serially while automatically incrementing the internal address count.

Write operations can be inhibited for upper half of memory by taking the WP pin High.

External address pins make it possible to address up to eight CAT24C03 or four CAT24C05 devices on the same bus.

#### Features

- Supports Standard and Fast I<sup>2</sup>C Protocol
- 1.8 V to 5.5 V Supply Voltage Range
- 16-Byte Page Write Buffer
- Hardware Write Protection for Upper Half of Memory
- Schmitt Triggers and Noise Suppression Filters on I<sup>2</sup>C Bus Inputs (SCL and SDA)
- Low Power CMOS Technology
- 1,000,000 Program/Erase Cycles
- 100 Year Data Retention
- Industrial Temperature Range
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

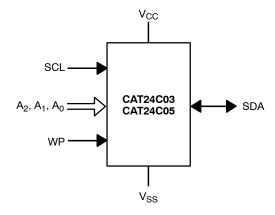
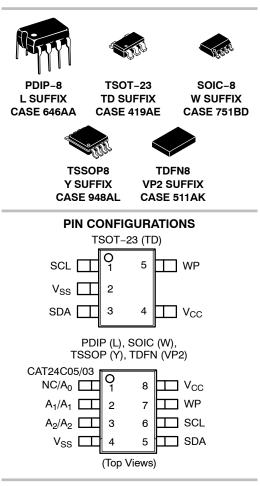


Figure 1. Functional Symbol



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#### **PIN FUNCTION**

| Function                 |
|--------------------------|
| Device Address Inputs    |
| Serial Data Input/Output |
| Serial Clock Input       |
| Write Protect Input      |
| Power Supply             |
| Ground                   |
| No Connect               |
|                          |

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 14 of this data sheet.

#### Table 1. ABSOLUTE MAXIMUM RATINGS

| Parameters                                         | Ratings      | Units |
|----------------------------------------------------|--------------|-------|
| Storage Temperature                                | –65 to +150  | °C    |
| Voltage on any pin with respect to Ground (Note 1) | –0.5 to +6.5 | V     |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. The DC input voltage on any pin should not be lower than -0.5 V or higher than V<sub>CC</sub> + 0.5 V. During transitions, the voltage on any pin may undershoot to no less than -1.5 V or overshoot to no more than V<sub>CC</sub> + 1.5 V, for periods of less than 20 ns.

#### Table 2. RELIABILITY CHARACTERISTICS (Note 2)

| Symbol                    | Parameter      | Min       | Units                  |
|---------------------------|----------------|-----------|------------------------|
| N <sub>END</sub> (Note 3) | Endurance      | 1,000,000 | Program / Erase Cycles |
| T <sub>DR</sub>           | Data Retention | 100       | Years                  |

2. These parameters are tested initially and after a design or process change that affects the parameter according to appropriate AEC-Q100 and JEDEC test methods.

3. Page Mode,  $V_{CC}$  = 5 V, 25°C.

#### Table 3. D.C. OPERATING CHARACTERISTICS

(V\_{CC} = 1.8 V to 5.5 V,  $T_A$  =  $-40^\circ C$  to +85°C, unless otherwise specified.)

| Symbol           | Parameter          | Test Conditions                                           | Min                   | Max                   | Units |
|------------------|--------------------|-----------------------------------------------------------|-----------------------|-----------------------|-------|
| I <sub>CCR</sub> | Read Current       | Read, f <sub>SCL</sub> = 400 kHz                          |                       | 1                     | mA    |
| I <sub>CCW</sub> | Write Current      | Write, f <sub>SCL</sub> = 400 kHz                         |                       | 1                     | mA    |
| I <sub>SB</sub>  | Standby Current    | All I/O Pins at GND or $V_{CC}$                           |                       | 1                     | μA    |
| ١L               | I/O Pin Leakage    | Pin at GND or $V_{CC}$                                    |                       | 1                     | μA    |
| V <sub>IL</sub>  | Input Low Voltage  |                                                           | -0.5                  | V <sub>CC</sub> x 0.3 | V     |
| V <sub>IH</sub>  | Input High Voltage |                                                           | V <sub>CC</sub> x 0.7 | V <sub>CC</sub> + 0.5 | V     |
| V <sub>OL1</sub> | Output Low Voltage | $V_{CC} \ge 2.5 \text{ V}, \text{ I}_{OL} = 3 \text{ mA}$ |                       | 0.4                   | V     |
| V <sub>OL2</sub> | Output Low Voltage | $V_{CC}$ < 2.5 V, $I_{OL}$ = 1 mA                         |                       | 0.2                   | V     |

#### **Table 4. PIN IMPEDANCE CHARACTERISTICS**

(V\_{CC} = 1.8 V to 5.5 V, T<sub>A</sub> = –40°C to +85°C, unless otherwise specified.)

| Symbol                   | Parameter                      | Conditions                        | Max | Units |
|--------------------------|--------------------------------|-----------------------------------|-----|-------|
| C <sub>IN</sub> (Note 4) | SDA I/O Pin Capacitance        | V <sub>IN</sub> = 0 V             | 8   | pF    |
|                          | Input Capacitance (Other Pins) | V <sub>IN</sub> = 0 V             | 6   | pF    |
| I <sub>WP</sub> (Note 5) | WP Input Current               | $V_{IN} < V_{IH}, V_{CC} = 5.5 V$ | 200 | μΑ    |
|                          |                                | $V_{IN} < V_{IH}, V_{CC} = 3.3 V$ | 150 |       |
|                          |                                | $V_{IN} < V_{IH}, V_{CC} = 1.8 V$ | 100 |       |
|                          |                                | $V_{IN} > V_{IH}$                 | 1   |       |

4. These parameters are tested initially and after a design or process change that affects the parameter according to appropriate AEC-Q100 and JEDEC test methods.

5. When not driven, the WP pin is pulled down to GND internally. For improved noise immunity, the internal pull-down is relatively strong; therefore the external driver must be able to supply the pull-down current when attempting to drive the input HIGH. To conserve power, as the input level exceeds the trip point of the CMOS input buffer (~ 0.5 x V<sub>CC</sub>), the strong pull-down reverts to a weak current source.

#### Table 5. A.C. CHARACTERISTICS

(Note 6) (V<sub>CC</sub> = 1.8 V to 5.5 V,  $T_A = -40^{\circ}$ C to +85°C, unless otherwise specified.)

|                              |                                            |     | dard | Fast |     |       |
|------------------------------|--------------------------------------------|-----|------|------|-----|-------|
| Symbol                       | Parameter                                  | Min | Max  | Min  | Max | Units |
| F <sub>SCL</sub>             | Clock Frequency                            |     | 100  |      | 400 | kHz   |
| t <sub>HD:STA</sub>          | START Condition Hold Time                  | 4   |      | 0.6  |     | μs    |
| t <sub>LOW</sub>             | Low Period of SCL Clock                    | 4.7 |      | 1.3  |     | μs    |
| t <sub>HIGH</sub>            | High Period of SCL Clock                   | 4   |      | 0.6  |     | μs    |
| t <sub>SU:STA</sub>          | START Condition Setup Time                 | 4.7 |      | 0.6  |     | μs    |
| t <sub>HD:DAT</sub>          | Data In Hold Time                          | 0   |      | 0    |     | μs    |
| t <sub>SU:DAT</sub>          | Data In Setup Time                         | 250 |      | 100  |     | ns    |
| t <sub>R</sub>               | SDA and SCL Rise Time                      |     | 1000 |      | 300 | ns    |
| t <sub>F</sub> (Note 7)      | SDA and SCL Fall Time                      |     | 300  |      | 300 | ns    |
| t <sub>SU:STO</sub>          | STOP Condition Setup Time                  | 4   |      | 0.6  |     | μs    |
| t <sub>BUF</sub>             | Bus Free Time Between STOP and START       | 4.7 |      | 1.3  |     | μs    |
| t <sub>AA</sub>              | SCL Low to Data Out Valid                  |     | 3.5  |      | 0.9 | μs    |
| t <sub>DH</sub>              | Data Out Hold Time                         | 100 |      | 100  |     | ns    |
| T <sub>i</sub> (Note 7)      | Noise Pulse Filtered at SCL and SDA Inputs |     | 100  |      | 100 | ns    |
| t <sub>SU:WP</sub>           | WP Setup Time                              | 0   | 1    | 0    | 1   | μs    |
| t <sub>HD:WP</sub>           | WP Hold Time                               | 2.5 | 1    | 2.5  | 1   | μs    |
| t <sub>WR</sub>              | Write Cycle Time                           |     | 5    |      | 5   | ms    |
| t <sub>PU</sub> (Notes 7, 8) | Power-up to Ready Mode                     |     | 1    |      | 1   | ms    |

6. Test conditions according to "A.C. Test Conditions" table.

7. Tested initially and after a design or process change that affects this parameter.

8.  $t_{PU}$  is the delay between the time  $V_{CC}$  is stable and the device is ready to accept commands.

#### Table 6. A.C. TEST CONDITIONS

| Input Levels              | 0.2 x V <sub>CC</sub> to 0.8 x V <sub>CC</sub>                                                 |
|---------------------------|------------------------------------------------------------------------------------------------|
| Input Rise and Fall Times | ≤ 50 ns                                                                                        |
| Input Reference Levels    | $0.3 \times V_{CC}, 0.7 \times V_{CC}$                                                         |
| Output Reference Levels   | 0.5 x V <sub>CC</sub>                                                                          |
| Output Load               | Current Source: I_{OL} = 3 mA (V_{CC} \ge 2.5 V); I_{OL} = 1 mA (V_{CC} < 2.5 V); C_L = 100 pF |

#### Power-On Reset (POR)

The CAT24C03/05 incorporates Power–On Reset (POR) circuitry which protects the internal logic against powering up in the wrong state.

The CAT24C03/05 device will power up into Standby mode after  $V_{CC}$  exceeds the POR trigger level and will power down into Reset mode when  $V_{CC}$  drops below the POR trigger level. This bi-directional POR feature protects the device against 'brown-out' failure following a temporary loss of power.

#### **Pin Description**

**SCL**: The Serial Clock input pin accepts the Serial Clock generated by the Master.

**SDA**: The Serial Data I/O pin receives input data and transmits data stored in EEPROM. In transmit mode, this pin is open drain. Data is acquired on the positive edge, and is delivered on the negative edge of SCL.

**A0, A1 and A2**: The Address inputs set the device address when cascading multiple devices. When not driven, these pins are pulled LOW internally.

**WP**: The Write Protect input pin inhibits the write operations for upper half of memory, when pulled HIGH. When not driven, this pin is pulled LOW internally.

#### **Functional Description**

The CAT24C03/05 supports the Inter–Integrated Circuit  $(I^2C)$  Bus data transmission protocol, which defines a device that sends data to the bus as a transmitter and a device receiving data as a receiver. Data flow is controlled by a Master device, which generates the serial clock and all START and STOP conditions. The CAT24C03/05 acts as a Slave device. Master and Slave alternate as either transmitter or receiver.

#### I<sup>2</sup>C Bus Protocol

The I<sup>2</sup>C bus consists of two 'wires', SCL and SDA. The two wires are connected to the  $V_{CC}$  supply via pull-up resistors. Master and Slave devices connect to the 2-wire bus via their respective SCL and SDA pins. The transmitting

device pulls down the SDA line to 'transmit' a '0' and releases it to 'transmit' a '1'.

Data transfer may be initiated only when the bus is not busy (see A.C. Characteristics).

During data transfer, the SDA line must remain stable while the SCL line is high. An SDA transition while SCL is HIGH will be interpreted as a START or STOP condition (Figure 2). The START condition precedes all commands. It consists of a HIGH to LOW transition on SDA while SCL is HIGH. The START acts as a 'wake-up' call to all receivers. Absent a START, a Slave will not respond to commands. The STOP condition completes all commands. It consists of a LOW to HIGH transition on SDA while SCL is HIGH.

#### **Device Addressing**

The Master initiates data transfer by creating a START condition on the bus. The Master then broadcasts an 8-bit serial Slave address. For normal Read/Write operations, the first 4 bits of the Slave address are fixed at 1010 (Ah). The next 3 bits are used as programmable address bits when cascading multiple devices and/or as internal address bits. The last bit of the slave address, R/W, specifies whether a Read (1) or Write (0) operation is to be performed. The 3 address space extension bits are assigned as illustrated in Figure 3. A<sub>2</sub>, A<sub>1</sub> and A<sub>0</sub> must match the state of the external address pins, and a<sub>8</sub> (CAT24C05) is internal address bit.

#### Acknowledge

After processing the Slave address, the Slave responds with an acknowledge (ACK) by pulling down the SDA line during the 9th clock cycle (Figure 4). The Slave will also acknowledge the address byte and every data byte presented in Write mode. In Read mode the Slave shifts out a data byte, and then releases the SDA line during the 9<sup>th</sup> clock cycle. As long as the Master acknowledges the data, the Slave will continue transmitting. The Master terminates the session by not acknowledging the last data byte (NoACK) and by issuing a STOP condition. Bus timing is illustrated in Figure 5.

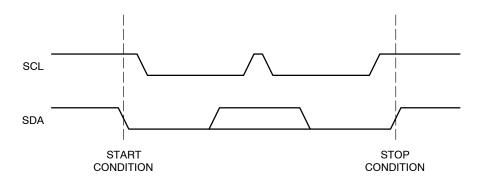
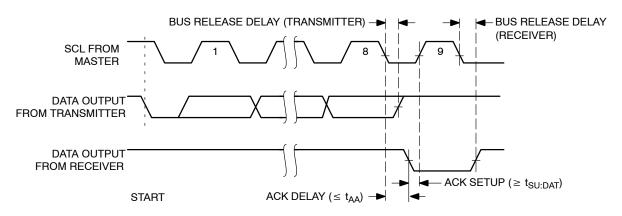
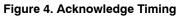


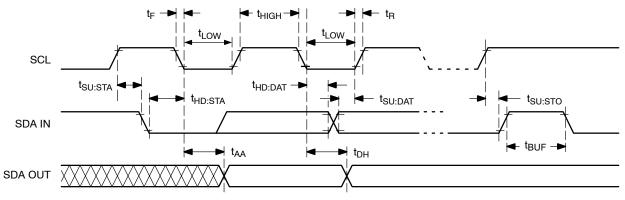
Figure 2. START/STOP Conditions

| 1 | 0 | 1 | 0 | A <sub>2</sub> | A <sub>1</sub> | A <sub>0</sub> | R/W | CAT24C03 |
|---|---|---|---|----------------|----------------|----------------|-----|----------|
| 1 | 0 | 1 | 0 | A <sub>2</sub> | A <sub>1</sub> | a <sub>8</sub> | R/W | CAT24C05 |

Figure 3. Slave Address Bits









#### WRITE OPERATIONS

#### **Byte Write**

In Byte Write mode, the Master sends the START condition and the Slave address with the R/W bit set to zero to the Slave. After the Slave generates an acknowledge, the Master sends the byte address that is to be written into the address pointer of the CAT24C03/05. After receiving another acknowledge from the Slave, the Master transmits the data byte to be written into the addressed memory location. The CAT24C03/05 device will acknowledge the data byte and the Master generates the STOP condition, at which time the device begins its internal Write cycle to nonvolatile memory (Figure 6). While this internal cycle is in progress (t<sub>WR</sub>), the SDA output will be tri–stated and the CAT24C03/05 will not respond to any request from the Master device (Figure 7).

#### Page Write

The CAT24C03/05 writes up to 16 bytes of data in a single write cycle, using the Page Write operation (Figure 8). The Page Write operation is initiated in the same manner as the Byte Write operation, however instead of terminating after the data byte is transmitted, the Master is allowed to send up to fifteen additional bytes. After each byte has been transmitted the CAT24C03/05 will respond with an acknowledge and internally increments the four low order address bits. The high order bits that define the page address remain unchanged. If the Master transmits more than sixteen bytes prior to sending the STOP condition, the address counter 'wraps around' to the beginning of page and previously transmitted data will be overwritten. Once all

sixteen bytes are received and the STOP condition has been sent by the Master, the internal Write cycle begins. At this point all received data is written to the CAT24C03/05 in a single write cycle.

#### Acknowledge Polling

The acknowledge (ACK) polling routine can be used to take advantage of the typical write cycle time. Once the stop condition is issued to indicate the end of the host's write operation, the CAT24C03/05 initiates the internal write cycle. The ACK polling can be initiated immediately. This involves issuing the start condition followed by the slave address for a write operation. If the CAT24C03/05 is still busy with the write operation, NoACK will be returned. If the CAT24C03/05 has completed the internal write operation, an ACK will be returned and the host can then proceed with the next read or write operation.

#### Hardware Write Protection

With the WP pin held HIGH, the upper half of memory is protected against Write operations. If the WP pin is left floating or is grounded, it has no impact on the operation of the CAT24C03/05. The state of the WP pin is strobed on the last falling edge of SCL immediately preceding the first data byte (Figure 9). If the WP pin is HIGH during the strobe interval, the CAT24C03/05 will not acknowledge the data byte and the Write request will be rejected.

#### **Delivery State**

The CAT24C03/05 is shipped erased, i.e., all bytes are FFh.

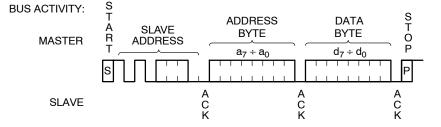
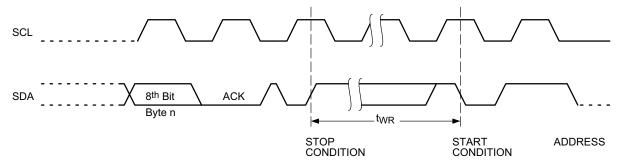
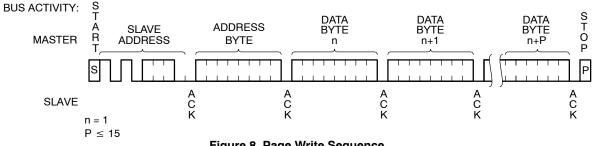
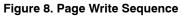


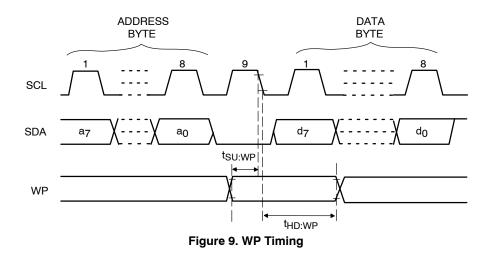
Figure 6. Byte Write Sequence











## **READ OPERATIONS**

#### Immediate Read

Upon receiving a Slave address with the R/W bit set to '1', the CAT24C03/05 will interpret this as a request for data residing at the current byte address in memory. The CAT24C03/05 will acknowledge the Slave address, will immediately shift out the data residing at the current address, and will then wait for the Master to respond. If the Master does not acknowledge the data (NoACK) and then follows up with a STOP condition (Figure 10), the CAT24C03/05 returns to Standby mode.

#### Selective Read

Selective Read operations allow the Master device to select at random any memory location for a read operation. The Master device first performs a 'dummy' write operation by sending the START condition, slave address and byte address of the location it wishes to read. After the CAT24C03/05 acknowledges the byte address, the Master device resends the START condition and the slave address, this time with the R/W bit set to one. The CAT24C03/05 then responds with its acknowledge and sends the requested data byte. The Master device does not acknowledge the data (NoACK) but will generate a STOP condition (Figure 11).

#### Sequential Read

If during a Read session, the Master acknowledges the 1<sup>st</sup> data byte, then the CAT24C03/05 will continue transmitting data residing at subsequent locations until the Master responds with a NoACK, followed by a STOP (Figure 12). In contrast to Page Write, during Sequential Read the address count will automatically increment to and then wrap–around at end of memory (rather than end of page).

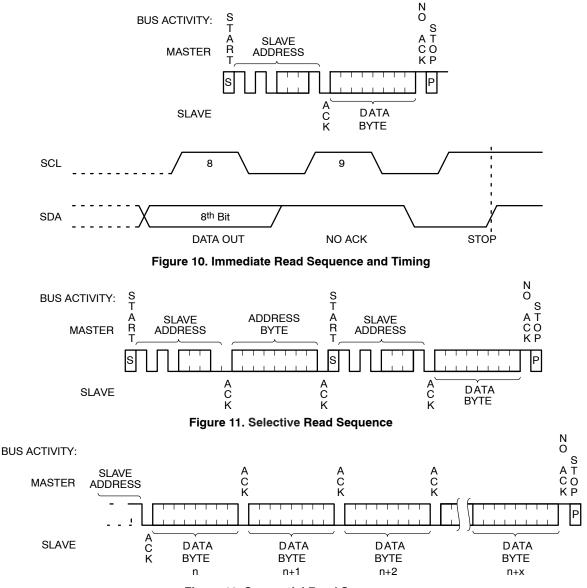
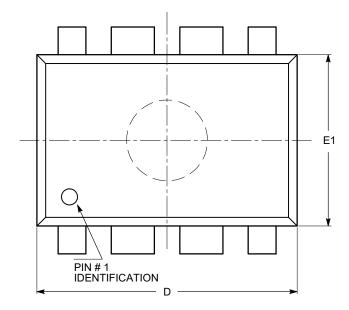


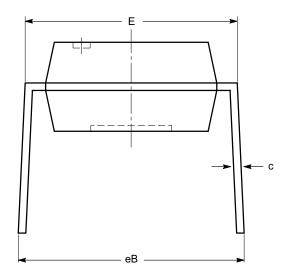
Figure 12. Sequential Read Sequence

#### PACKAGE DIMENSIONS

PDIP-8, 300 mils CASE 646AA-01 ISSUE A

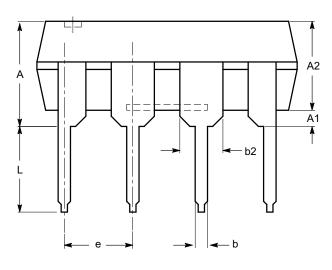


| SYMBOL | MIN  | NOM      | MAX   |
|--------|------|----------|-------|
| А      |      |          | 5.33  |
| A1     | 0.38 |          |       |
| A2     | 2.92 | 3.30     | 4.95  |
| b      | 0.36 | 0.46     | 0.56  |
| b2     | 1.14 | 1.52     | 1.78  |
| с      | 0.20 | 0.25     | 0.36  |
| D      | 9.02 | 9.27     | 10.16 |
| Е      | 7.62 | 7.87     | 8.25  |
| E1     | 6.10 | 6.35     | 7.11  |
| е      |      | 2.54 BSC |       |
| eB     | 7.87 |          | 10.92 |
| L      | 2.92 | 3.30     | 3.80  |



END VIEW

TOP VIEW



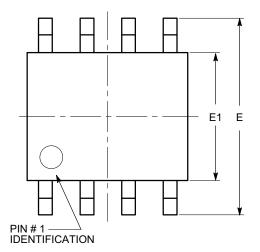
SIDE VIEW

#### Notes:

- (1) All dimensions are in millimeters.
- (2) Complies with JEDEC MS-001.

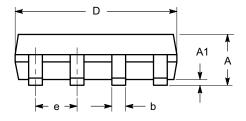
## PACKAGE DIMENSIONS

SOIC 8, 150 mils CASE 751BD-01 ISSUE O



TOP VIEW

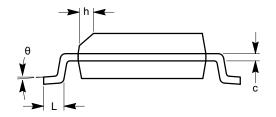
| SYMBOL | MIN  | NOM      | MAX  |
|--------|------|----------|------|
| А      | 1.35 |          | 1.75 |
| A1     | 0.10 |          | 0.25 |
| b      | 0.33 |          | 0.51 |
| с      | 0.19 |          | 0.25 |
| D      | 4.80 |          | 5.00 |
| E      | 5.80 |          | 6.20 |
| E1     | 3.80 |          | 4.00 |
| е      |      | 1.27 BSC |      |
| h      | 0.25 |          | 0.50 |
| L      | 0.40 |          | 1.27 |
| θ      | 0°   |          | 8°   |



SIDE VIEW

#### Notes:

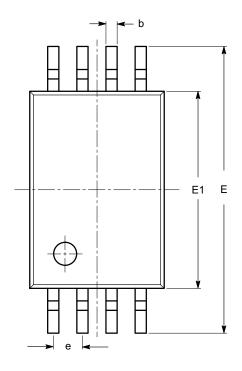
(1) All dimensions are in millimeters. Angles in degrees.
(2) Complies with JEDEC MS-012.



END VIEW

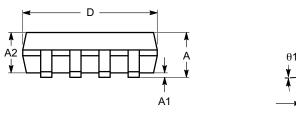
## PACKAGE DIMENSIONS

TSSOP8, 4.4x3 CASE 948AL-01 ISSUE O

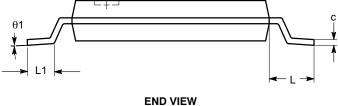


| SYMBOL | MIN      | NOM      | MAX  |  |  |
|--------|----------|----------|------|--|--|
| А      |          |          | 1.20 |  |  |
| A1     | 0.05     |          | 0.15 |  |  |
| A2     | 0.80     | 0.90     | 1.05 |  |  |
| b      | 0.19     |          | 0.30 |  |  |
| с      | 0.09     |          | 0.20 |  |  |
| D      | 2.90     | 3.00     | 3.10 |  |  |
| E      | 6.30     | 6.40     | 6.50 |  |  |
| E1     | 4.30     | 4.40     | 4.50 |  |  |
| е      |          | 0.65 BSC |      |  |  |
| L      | 1.00 REF |          |      |  |  |
| L1     | 0.50     | 0.60     | 0.75 |  |  |
| θ      | 0°       |          | 8°   |  |  |





SIDE VIEW

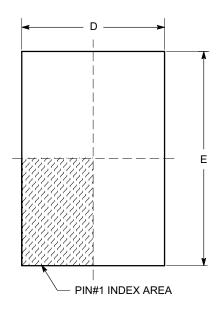


Notes:

All dimensions are in millimeters. Angles in degrees.
Complies with JEDEC MO-153.

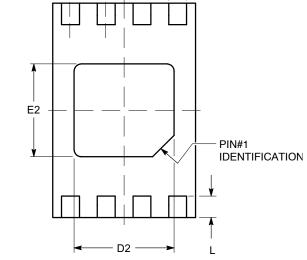
#### PACKAGE DIMENSIONS

TDFN8, 2x3 CASE 511AK-01 ISSUE A





– A –



b

е

TOP VIEW

SIDE VIEW

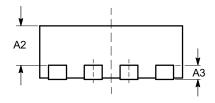
| SYMBOL | MIN      | NOM      | МАХ  |  |
|--------|----------|----------|------|--|
| А      | 0.70     | 0.75     | 0.80 |  |
| A1     | 0.00     | 0.02     | 0.05 |  |
| A2     | 0.45     | 0.55     | 0.65 |  |
| A3     |          | 0.20 REF |      |  |
| b      | 0.20     | 0.25     | 0.30 |  |
| D      | 1.90     | 2.00     | 2.10 |  |
| D2     | 1.30     | 1.40     | 1.50 |  |
| E      | 2.90     | 3.00     | 3.10 |  |
| E2     | 1.20     | 1.30     | 1.40 |  |
| е      | 0.50 TYP |          |      |  |
| L      | 0.20     | 0.30     | 0.40 |  |

Notes:

(1) All dimensions are in millimeters.

(2) Complies with JEDEC MO-229.

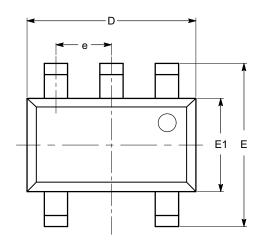
BOTTOM VIEW



FRONT VIEW

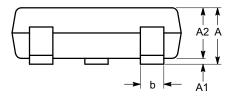
### PACKAGE DIMENSIONS

TSOT-23, 5 LEAD CASE 419AE-01 ISSUE O



| SYMBOL | MIN      | NOM  | MAX  |
|--------|----------|------|------|
| А      |          |      | 1.00 |
| A1     | 0.01     | 0.05 | 0.10 |
| A2     | 0.80     | 0.87 | 0.90 |
| b      | 0.30     |      | 0.45 |
| с      | 0.12     | 0.15 | 0.20 |
| D      | 2.90 BSC |      |      |
| E      | 2.80 BSC |      |      |
| E1     | 1.60 BSC |      |      |
| е      | 0.95 TYP |      |      |
| L      | 0.30     | 0.40 | 0.50 |
| L1     | 0.60 REF |      |      |
| L2     | 0.25 BSC |      |      |
| θ      | 0°       |      | 8°   |

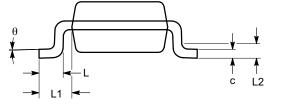
TOP VIEW



SIDE VIEW

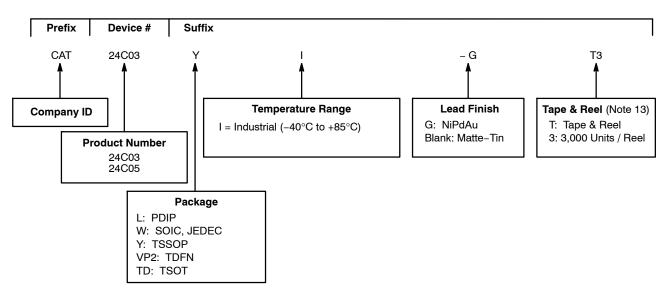
Notes:

- (1) All dimensions are in millimeters. Angles in degrees.
- (2) Complies with JEDEC MO-193.



END VIEW

#### Example of Ordering Information



9. All packages are RoHS-compliant (Lead-free, Halogen-free).

10. The standard lead finish is NiPdAu pre-plated (PPF) lead frames.

11. The device used in the above example is a CAT24C03YI-GT3 (TSSOP, Industrial Temperature, NiPdAu, Tape & Reel).

12. For additional package and temperature options, please contact your nearest ON Semiconductor Sales office.

13. For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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